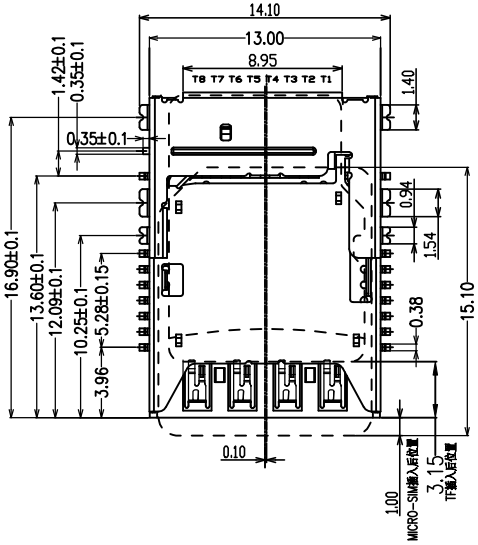
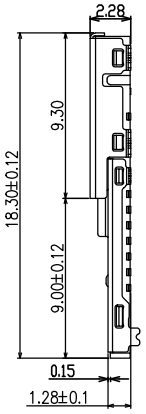
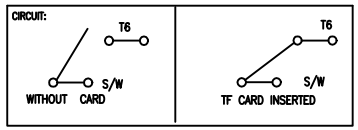
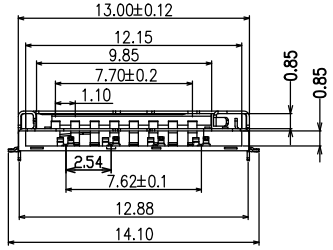
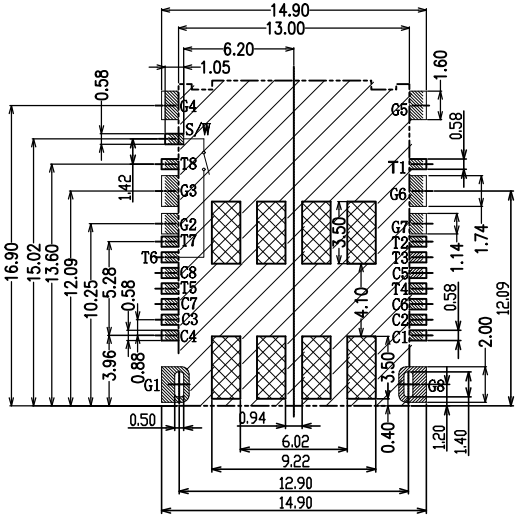
*ROHS





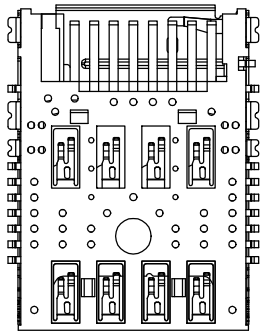


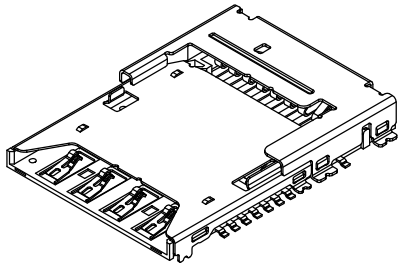




NO PATTERN AREA
NO CIRCUIT AREA
SOLDER AREA

P.C.B LAYOUT
(TOLERANCE±0.05)





NOTE:
一.材质及电镀方式 (MATERIAL AND FINISH)
1.塑胶 (HOUSING):LCP,
UL 94V-0 , COLOR:BLACK
2.端子 (CONTACT):COPPER ALLOY
Au 1u" PLATING ON CONTACT AREA,
GOLD FLASH PLATING ON SOLDER TAILS
50u" NICKEL UNDER PLATING OVER ALL
3.铁壳 (SHELL):SUS304-3/4H
40u" NICKEL UNDER PLATING OVER ALL
GOLD FLASH PLATING ON SOLDER TAILS

二.机械特性 (MECHANICAL CHARACTERISTICS)
1.插入力 (Insertion Force): 2.0Kgf Max
2.拔出力 (Withdrawal Force): 0.1Kgf Min
3.耐久性(Durability): 1500次

三.电气特性
1.额定电流 (Current rating): 0.5A AC/DC
2.接触电阻 (Contact resistance): 100mΩ MAX
3.绝缘电阻 (Insulation resistance): 500MΩ MIN
4.适用温度 (Operating temperature): -20℃~85℃

TF CARD PIN ASSIGNMENT

PIN NO.	PIN ASSIGNMENT
T1	DAT2
T2	CD/DAT3 [2]
T3	CMD
T4	VDD
T5	CLK
T6	VSS
T7	DAT0
T8	DAT1

SIM pin assignment	
	Name
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

广东国连电子有限公司
GUANGDONG GUOLIAN ELECTRONICS CO.,LTD

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.38
X.XX: ±	0.25
X.XXX: ±	0.10
ANGULAR: ±	1°

PRODUCT NAME :	DRAWING:	DATE:
micro sim + micro SD connector		2012/03/10
PRODUCT NO. : MMB1FW1162C2	CHECK:	DATE: 2012/03/11
DRAWING NO. : 003	APPROVED:	DATE: 2012/03/11
	SCALE: 1:1 / DWG ID: C D / REV.: A / PAGE: 1 OF 1	

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE

1 2 3 4 5 6